

Abstract of the Disclosure

0041        A matrix form semiconductor package substrate that has an electrode situated in-between a plurality of IC package substrates for providing electrical communication to conductive pads on the substrate is provided. The matrix form semiconductor package substrate includes a plurality of IC package substrates that are integrally formed on a strip in a matrix pattern that has a boundary between each two of the plurality of IC package substrates. Each of the plurality of IC package substrates has a multiplicity of conductive pad traces and an electrode, or a plating bar, formed in a serpentine configuration along the boundary for providing electrical communication to the multiplicity of conductive pads.